

Claim Amendments

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims

Claim 1. (Currently Amended) An electronic device, comprising:

a battery containing a nonaqueous solvent disposed on a substrate and an electronic circuit disposed adjacent to the battery, wherein the electronic circuit is isolated from the battery by an epoxy resin composition comprising:

- (a) an epoxy resin,
- (b) a latent catalyst consisting of a phenol compound and an organic metal compound,
- (c) a butyral resin, and

(d) an inorganic filler, whereby ~~in the event of leakage of nonaqueous solvent from the battery, deleterious contact of the leaked~~ electronic circuit is protected from any leakage of nonaqueous solvent with the electronic circuit is prevented from the battery.

Claim 2. (Previously Presented) The electronic device according to Claim 1, wherein the average particle diameter of said inorganic filler is 10 μm or less and the amount of the inorganic filler in said epoxy resin composition is 10 % by weight or more to 80 % by weight or less.

Claim 3. (Previously Presented) The electronic device according to Claim 1, wherein said organic metal compound is a metal complex.

Claim 4. (Previously Presented) The electronic device according to Claim 1, wherein said phenol compound is a bisphenol S and said organic metal compound is an organozirconium compound.

Claim 5. (Previously Presented) The electronic device according to Claim 1, wherein said epoxy resin is an epoxy resin homopolymer.

Claim 6. (Previously Presented) The electronic device according to Claim 2, wherein said organic metal compound is a metal complex.

Claim 7. (Previously Presented) The electronic device according to Claim 2, wherein said phenol compound is a bisphenol S and said metal complex is an organozirconium compound.

Claim 8. (Previously Presented) The electronic device according to Claim 2, wherein said epoxy resin is an epoxy resin homopolymer.

Claim 9. (Withdrawn) The electronic device according to Claim 1, wherein said epoxy resin composition covers said electronic circuit.

Claim 10. (Previously Presented) The electronic device according to Claim 1, wherein said epoxy resin composition covers said battery containing a nonaqueous solvent.

Claim 11. (Withdrawn) The electronic device according to Claim 1, wherein said epoxy resin composition is molded into the form of a container and the container encloses said battery containing a nonaqueous solvent.

Claim 12. (Withdrawn) The electronic device according to Claim 1, wherein said epoxy resin composition is molded into the form of a container and the container encloses said electronic circuit.

Claim 13. (Previously Presented) The electronic device according to Claim 1, wherein said electronic circuit is a control circuit for a secondary battery containing a nonaqueous solvent.

Claim 14. (Previously Presented) The electronic device according to Claim 1, wherein said electronic circuit is a protective circuit for a secondary battery containing a nonaqueous solvent.

Claim 15. (Currently Amended) An electronic device, comprising:

a battery containing a nonaqueous electrolyte and a protective circuit for the battery arranged adjacent to the battery, the protective circuit for the battery being coated with an epoxy resin composition containing an epoxy resin, a latent catalyst consisting of a phenol compound and an organic metal compound, a butyral resin and an inorganic filler, whereby in the event of leakage of nonaqueous solvent from the battery, deleterious contact of the leaked electronic circuit is protected from any leakage of nonaqueous solvent with the electronic circuit is prevented from the battery.

Claim 16. (Previously Presented) The electronic device according to Claim 15, wherein the average particle diameter of said inorganic filler is 10 μm or less and the amount of the inorganic filler in said epoxy resin composition is 10 % by weight or more to 80 % by weight or less.

Claim 17. (Previously Presented) The electronic device according to Claim 15, wherein said organic metal compound is a metal complex.

Claim 18. (Previously Presented) The electronic device according to Claim 15, wherein said phenol compound is a bisphenol S and said organic metal compound is an organozirconium compound.

Claim 19. (Previously Presented) The electronic device according to Claim 15, wherein said epoxy resin is an epoxy resin homopolymer.

Claim 20. (Currently Amended) An electronic device, comprising:
a battery containing a nonaqueous solvent disposed on a substrate and an electronic circuit disposed adjacent to the battery, wherein the electronic circuit is isolated from the battery by an epoxy resin composition which covers the battery containing a nonaqueous solvent comprising:

- (a) a bisphenol F epoxy resin,
- (b₁) a latent catalyst consisting of 4,4'-dihydroxydiphenylsulfone and
- (b₂) zirconium tetraacetylacetonate,
- (c) a butyral resin, and

(d) silica, whereby ~~in the event of leakage of nonaqueous solvent from the battery,~~
~~deleterious contact of the leaked~~ electronic circuit is protected from any leakage of
nonaqueous solvent ~~with the electronic circuit is prevented~~ from the battery.